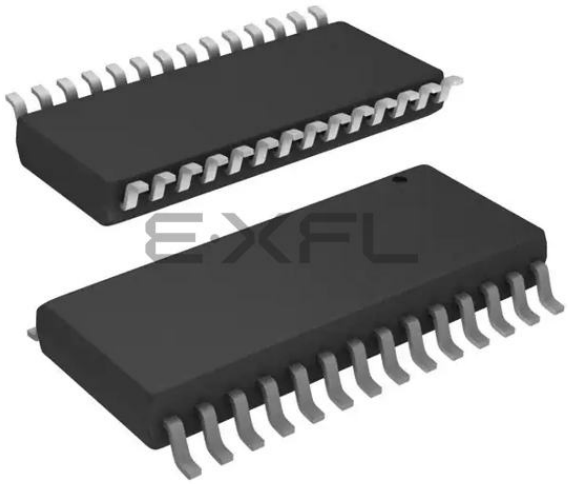
Microchip Technology - DSPIC33EV64GM002T-I/SO Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm002t-i-so

dsPIC33EVXXXGM00X/10X PRODUCT FAMILIES

The device names, pin counts, memory sizes and peripheral availability of each device are listed in Table 1. The following pages show the devices' pinout diagrams.

TABLE 1: dsPIC33EVXXXGM00X/10X FAMILY DEVICES

Device	Program Memory Bytes	SRAM Bytes	CAN	DMA Channels	16-Bit Timers (T1)	32-Bit Timers	Input Capture	Output Compare	PWM	UART	SPI	I^2C	SENT	10/12-Bit ADC	ADC Inputs	Op Amp/Comparators	CTMU	Security	Peripheral Pin Select (PPS)	General Purpose I/O (GPIO)	External Interrupts	Pins	Packages
dsPIC33EV32GM002	32K	4K	0	4	5	2	4	4	3x2	2	2	1	2	1	11	3/4	1	Intermediate	Y	21	3	28	SPDIP, SOIC, SSOP, QFN-S
dsPIC33EV32GM102			1																				
dsPIC33EV64GM002	64K	8K	0																				
dsPIC33EV64GM102			1																				
dsPIC33EV128GM002	128K	8K	0																				
dsPIC33EV128GM102			1																				
dsPIC33EV256GM002	256K	16K	0																				
dsPIC33EV256GM102			1																				
dsPIC33EV32GM004	32K	4K	0	4	5	2	4	4	3x2	2	2	1	2	1	24	4/5	1	Intermediate	Y	35	3	44	TQFP, QFN
dsPIC33EV32GM104			1																				
dsPIC33EV64GM004	64K	8K	0																				
dsPIC33EV64GM104			1																				
dsPIC33EV128GM004	128K	8K	0																				
dsPIC33EV128GM104			1																				
dsPIC33EV256GM004	256K	16K	0																				
dsPIC33EV256GM104			1																				
dsPIC33EV32GM006	32K	4K	0	4	5	2	4	4	3x2	2	2	1	2	1	36	4/5	1	Intermediate	Y	53	3	64	TQFP, QFN
dsPIC33EV32GM106			1																				
dsPIC33EV64GM006	64K	8K	0																				
dsPIC33EV64GM106			1																				
dsPIC33EV128GM006	128K	8K	0																				
dsPIC33EV128GM106			1																				
dsPIC33EV256GM006	256K	16K	0																				
dsPIC33EV256GM106			1																				

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EVXXXGM00X/10X family of 16-bit microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

Note: The AVDD and AVSS pins must be connected, regardless of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10V-20V is recommended. This capacitor should be a Low Equivalent Series Resistance (low-ESR), and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the Printed Circuit Board (PCB):** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing the PCB track inductance.

REGISTER 10-7: PMD8: PERIPHERAL MODULE DISABLE CONTROL REGISTER 8

U-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	R/W-0
—	—	—	SENT2MD	SENT1MD	—	—	DMTMD
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **SENT2MD:** SENT2 Module Disable bit
1 = SENT2 module is disabled
0 = SENT2 module is enabled

bit 11 **SENT1MD:** SENT1 Module Disable bit
1 = SENT1 module is disabled
0 = SENT1 module is enabled

bit 10-9 **Unimplemented:** Read as ‘0’

bit 8 **DMTMD:** Deadman Timer Disable bit
1 = Deadman Timer is disabled
0 = Deadman Timer is enabled

bit 7-0 **Unimplemented:** Read as ‘0’

NOTES:

REGISTER 11-5: RPINR8: PERIPHERAL PIN SELECT INPUT REGISTER 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC4R7	IC4R6	IC4R5	IC4R4	IC4R3	IC4R2	IC4R1	IC4R0
bit 15							bit 8

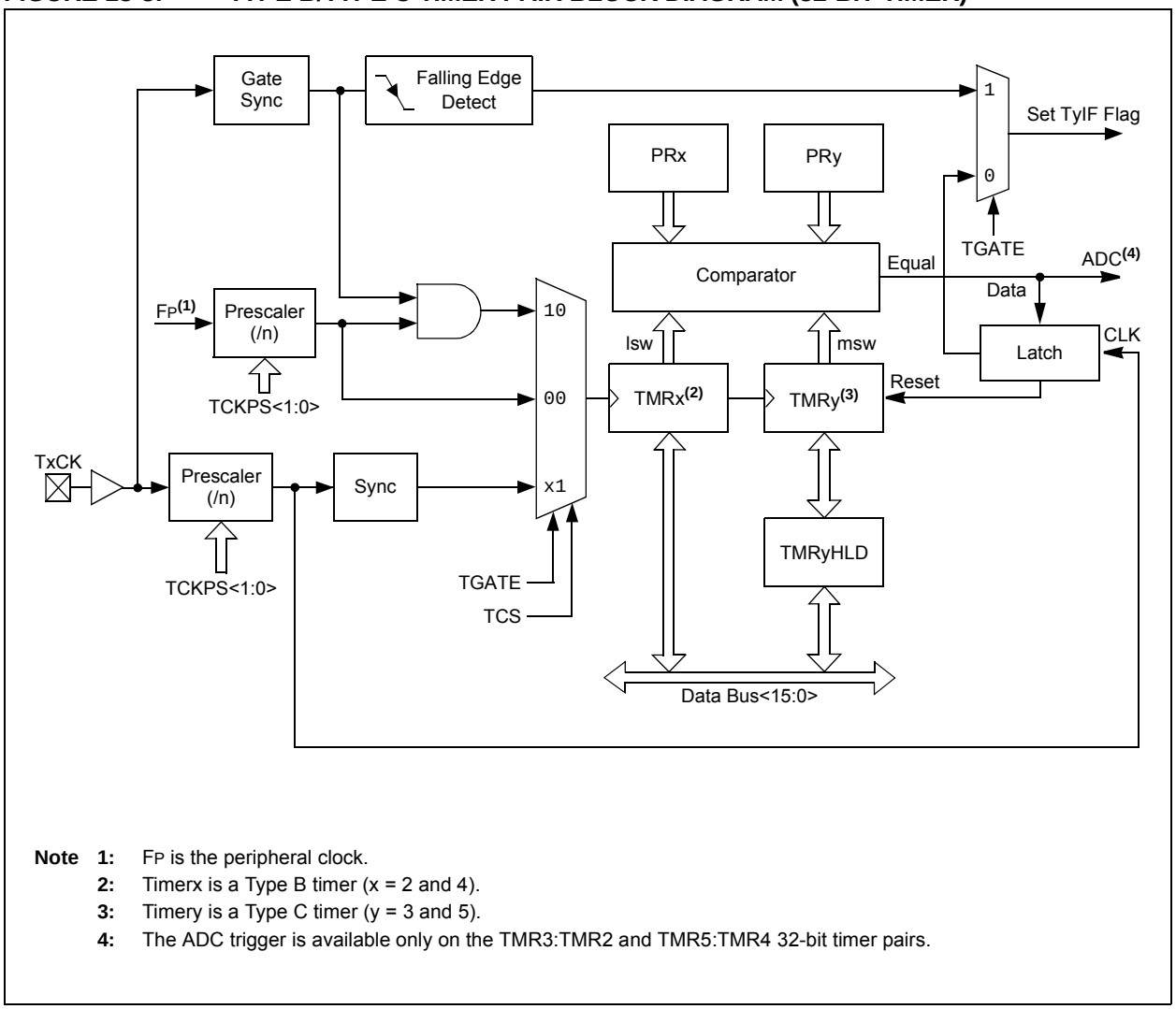
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC3R7	IC3R6	IC3R5	IC3R4	IC3R3	IC3R2	IC3R1	IC3R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **IC4R<7:0>:** Assign Input Capture 4 (IC4) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

bit 7-0 **IC3R<7:0>:** Assign Input Capture 3 (IC3) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

FIGURE 13-3: TYPE B/TYPE C TIMER PAIR BLOCK DIAGRAM (32-BIT TIMER)



Note 1: FP is the peripheral clock.
2: Timerx is a Type B timer (x = 2 and 4).
3: Timery is a Type C timer (y = 3 and 5).
4: The ADC trigger is available only on the TMR3:TMR2 and TMR5:TMR4 32-bit timer pairs.

REGISTER 14-7: DMTPSCNTL: DMT POST CONFIGURE COUNT STATUS REGISTER LOW

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSCNT<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PSCNT<15:0>:** Lower DMT Instruction Count Value Configuration Status bits
This is always the value of the FDMTCNTL Configuration register.

REGISTER 14-8: DMTPSCNTH: DMT POST CONFIGURE COUNT STATUS REGISTER HIGH

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSCNT<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSCNT<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PSCNT<31:16>:** Higher DMT Instruction Count Value Configuration Status bits
This is always the value of the FDMTCNTH Configuration register.

REGISTER 17-1: PTCON: PWMx TIME BASE CONTROL REGISTER (CONTINUED)

bit 6-4 **SYNCSRC<2:0>:** Synchronous Source Selection bits(1)
111 = Reserved
•
•
•
100 = Reserved
011 = Reserved
010 = Reserved
001 = Reserved
000 = SYNCI1 input from PPS

bit 3-0 **SEVTPS<3:0>:** Special Event Trigger Output Postscaler Select bits(1)
1111 = 1:16 postscaler generates a Special Event Trigger on every sixteenth compare match event
•
•
•
0001 = 1:2 postscaler generates a Special Event Trigger on every second compare match event
0000 = 1:1 postscaler generates a Special Event Trigger on every compare match event

Note 1: These bits should be changed only when PTEN = 0. In addition, when using the SYNCI1 feature, the user application must program the Period register with a value that is slightly larger than the expected period of the external synchronization input signal.

REGISTER 17-2: PTCON2: PWMx PRIMARY MASTER CLOCK DIVIDER SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PCLKDIV<2:0>(1)		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as '0'

bit 2-0 **PCLKDIV<2:0>:** PWMx Input Clock Prescaler (Divider) Select bits(1)
111 = Reserved
110 = Divide-by-64
101 = Divide-by-32
100 = Divide-by-16
011 = Divide-by-8
010 = Divide-by-4
001 = Divide-by-2
000 = Divide-by-1, maximum PWMx timing resolution (power-on default)

Note 1: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

20.3 Receive Mode

The module can be configured for receive operation by setting the RCVEN (SENTxCON1<11>) bit. The time between each falling edge is compared to SYNCMIN<15:0> (SENTxCON3<15:0>) and SYNCMAX<15:0> (SENTxCON2<15:0>), and if the measured time lies between the minimum and maximum limits, the module begins to receive data. The validated Sync time is captured in the SENTxSYNC register and the tick time is calculated. Subsequent falling edges are verified to be within the valid data width and the data is stored in the SENTxDATH/L register. An interrupt event is generated at the completion of the message and the user software should read the SENTx Data register before the reception of the next nibble. The equation for SYNCMIN<15:0> and SYNCMAX<15:0> is shown in Equation 20-3.

EQUATION 20-3: SYNCMIN<15:0> AND SYNCMAX<15:0> CALCULATIONS

$$T_{TICK} = T_{CLK} \bullet (TICKTIME\langle 15{:}0\rangle + 1)$$

$$FRAMETIME\langle 15{:}0\rangle = T_{TICK}/T_{FRAME}$$

$$SyncCount = 8 \times F_{RCV} \times T_{TICK}$$

$$SYNCMIN\langle 15{:}0\rangle = 0.8 \times SyncCount$$

$$SYNCMAX\langle 15{:}0\rangle = 1.2 \times SyncCount$$

$$FRAMETIME\langle 15{:}0\rangle \geq 122 + 27N$$

$$FRAMETIME\langle 15{:}0\rangle \geq 848 + 12N$$

Where:
T_{FRAME} = Total time of the message from ms
N = The number of data nibbles in message, 1-6
F_{RCV} = FCY x prescaler
T_{CLK} = FCY/Prescaler

For TTICK = 3.0 µs and FCLK = 4 MHz, SYNCMIN<15:0> = 76.

Note: To ensure a Sync period can be identified, the value written to SYNCMIN<15:0> must be less than the value written to SYNCMAX<15:0>.

20.3.1 RECEIVE MODE CONFIGURATION

20.3.1.1 Initializing the SENTx Module:

Perform the following steps to initialize the module:

1. Write RCVEN (SENTxCON1<11>) = 1 for Receive mode.
2. Write NIBCNT<2:0> (SENTxCON1<2:0>) for the desired data frame length.
3. Write CRCEN (SENTxCON1<8>) for hardware or software CRC validation.
4. Write PPP (SENTxCON1<7>) = 1 if pause pulse is present.
5. Write SENTxCON2 with the value of SYNCMAXx (Nominal Sync Period + 20%).
6. Write SENTxCON3 with the value of SYNCMINx (Nominal Sync Period – 20%).
7. Enable interrupts and set interrupt priority.
8. Set the SNTEN (SENTxCON1<15>) bit to enable the module.

The data should be read from the SENTxDATH/L register after the completion of the CRC and before the next message frame's status nibble. The recommended method is to use the message frame completion interrupt trigger.

NOTES:

REGISTER 24-4: ADxCON4: ADCx CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ADDMAEN
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	DMABL2	DMABL1	DMABL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **ADDMAEN:** ADCx DMA Enable bit

1 = Conversion results are stored in the ADC1BUF0 register for transfer to RAM using DMA
0 = Conversion results are stored in the ADC1BUF0 through ADC1BUFF registers; DMA will not be used

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **DMABL<2:0>:** Selects Number of DMA Buffer Locations per Analog Input bits

111 = Allocates 128 words of buffer to each analog input
110 = Allocates 64 words of buffer to each analog input
101 = Allocates 32 words of buffer to each analog input
100 = Allocates 16 words of buffer to each analog input
011 = Allocates 8 words of buffer to each analog input
010 = Allocates 4 words of buffer to each analog input
001 = Allocates 2 words of buffer to each analog input
000 = Allocates 1 word of buffer to each analog input

TABLE 27-1: CONFIGURATION WORD REGISTER MAP

File Name	Address	Device Memory Size (Kbytes)	Bits 23-16	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FSEC	005780	32	—	AIVTDIS	—	—	—	CSS2	CSS1	CSS0	CWRP	GSS1	GSS0	GWRP	—	BSEN	BSS1	BSS0	BWRP
	00AB80	64																	
	015780	128																	
	02AB80	256																	
FBSLIM	005790	32	—	—	—	—	BSLIM<12:0>												
	00AB90	64																	
	015790	128																	
	02AB90	256																	
Reserved	005794	32	—	Reserved(1)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
	00AB94	64																	
	015794	128																	
	02AB94	256																	
FOSCSEL	005798	32	—	—	—	—	—	—	—	—	—	$\overline{\text{IESO}}$	—	—	—	—	FNOSC2	FNOSC1	FNOSC0
	00AB98	64																	
	015798	128																	
	02AB98	256																	
FOSC	00579C	32	—	—	—	—	—	—	—	—	PLLKEN	FCKSM1	FCKSM0	IOL1WAY	—	—	OSCIOFNC	POSCMD1	POSCMD0
	00AB9C	64																	
	01579C	128																	
	02AB9C	256																	
FWDT	0057A0	32	—	—	—	—	—	—	—	WDTWIN1	WDTWIN0	WINDIS	FWDTEN1	FWDTEN0	WDTPRE	WDTPS3	WDTPS2	WDTPS1	WDTPS0
	00ABA0	64																	
	0157A0	128																	
	02ABA0	256																	
FPOR	0057A4	32	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	BOREN
	00ABA4	64																	
	0157A4	128																	
	02ABA4	256																	
FICD	0057A8	32	—	—	—	—	—	—	—	—	—	Reserved(2)	—	—	—	—	—	ICS1	ICS0
	00ABA8	64																	
	0157A8	128																	
	02ABA8	256																	

Legend: — = unimplemented, read as '1'.
Note 1: This bit is reserved and must be programmed as '0'.
2: This bit is reserved and must be programmed as '1'.

TABLE 28-2: INSTRUCTION SET OVERVIEW

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
1	ADD	ADD	Acc	Add Accumulators	1	1	OA,OB,SA, SB
		ADD	f	f = f + WREG	1	1	C,DC,N,OV,Z
		ADD	f,WREG	WREG = f + WREG	1	1	C,DC,N,OV,Z
		ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C,DC,N,OV,Z
		ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C,DC,N,OV,Z
		ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C,DC,N,OV,Z
		ADD	Wso,#Slit4,Acc	16-bit Signed Add to Accumulator	1	1	OA,OB,SA, SB
2	ADDC	ADDC	f	f = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C,DC,N,OV,Z
3	AND	AND	f	f = f .AND. WREG	1	1	N,Z
		AND	f,WREG	WREG = f .AND. WREG	1	1	N,Z
		AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N,Z
		AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N,Z
		AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N,Z
4	ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C,N,OV,Z
		ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N,Z
		ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N,Z
5	BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
		BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
6	BRA	BRA	C,Expr	Branch if Carry	1	1 (4)	None
		BRA	GE,Expr	Branch if greater than or equal	1	1 (4)	None
		BRA	GEU,Expr	Branch if unsigned greater than or equal	1	1 (4)	None
		BRA	GT,Expr	Branch if greater than	1	1 (4)	None
		BRA	GTU,Expr	Branch if unsigned greater than	1	1 (4)	None
		BRA	LE,Expr	Branch if less than or equal	1	1 (4)	None
		BRA	LEU,Expr	Branch if unsigned less than or equal	1	1 (4)	None
		BRA	LT,Expr	Branch if less than	1	1 (4)	None
		BRA	LTU,Expr	Branch if unsigned less than	1	1 (4)	None
		BRA	N,Expr	Branch if Negative	1	1 (4)	None
		BRA	NC,Expr	Branch if Not Carry	1	1 (4)	None
		BRA	NN,Expr	Branch if Not Negative	1	1 (4)	None
		BRA	NOV,Expr	Branch if Not Overflow	1	1 (4)	None
		BRA	NZ,Expr	Branch if Not Zero	1	1 (4)	None
		BRA	OA,Expr	Branch if Accumulator A overflow	1	1 (4)	None
		BRA	OB,Expr	Branch if Accumulator B overflow	1	1 (4)	None
		BRA	OV,Expr	Branch if Overflow	1	1 (4)	None
		BRA	SA,Expr	Branch if Accumulator A saturated	1	1 (4)	None
		BRA	SB,Expr	Branch if Accumulator B saturated	1	1 (4)	None
		BRA	Expr	Branch Unconditionally	1	4	None
		BRA	Z,Expr	Branch if Zero	1	1 (4)	None
		BRA	Wn	Computed Branch	1	4	None
7	BSET	BSET	f,#bit4	Bit Set f	1	1	None
		BSET	Ws,#bit4	Bit Set Ws	1	1	None

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

FIGURE 30-18: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

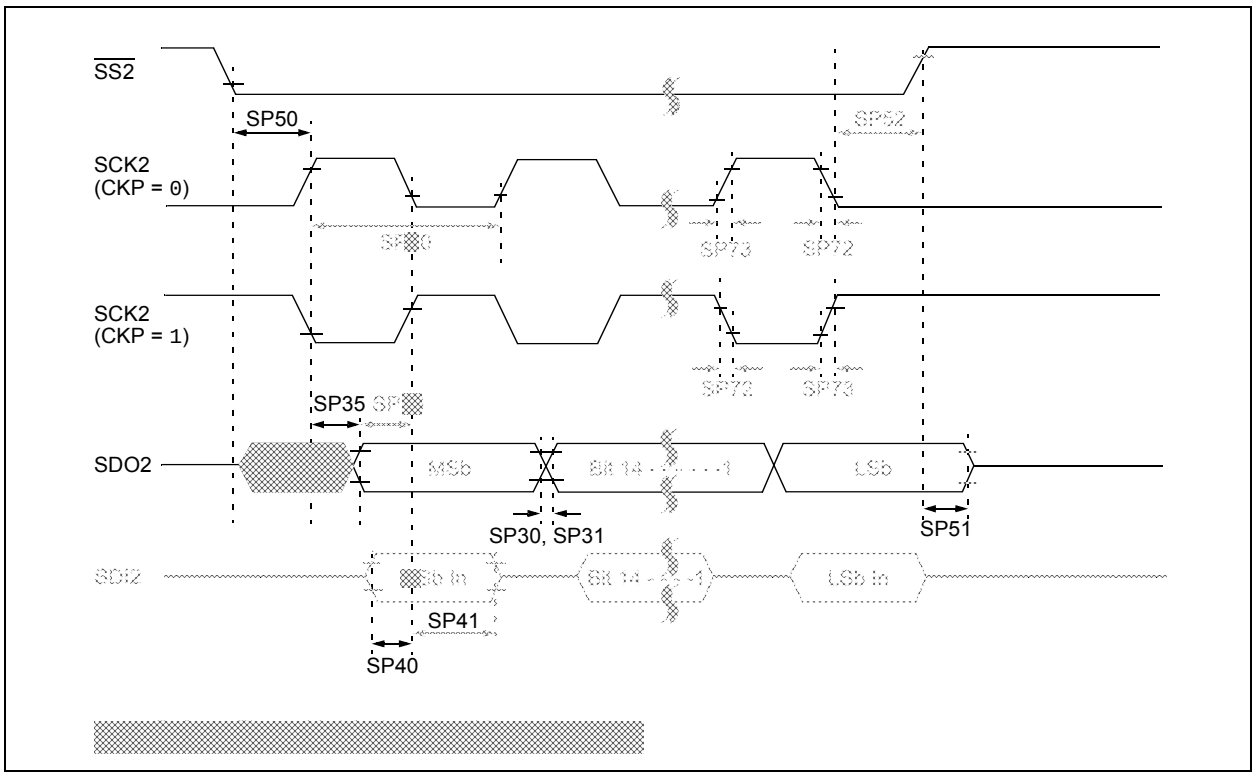


TABLE 30-42: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	25	MHz	See **Note 3**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	20	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCK1 Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	15	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

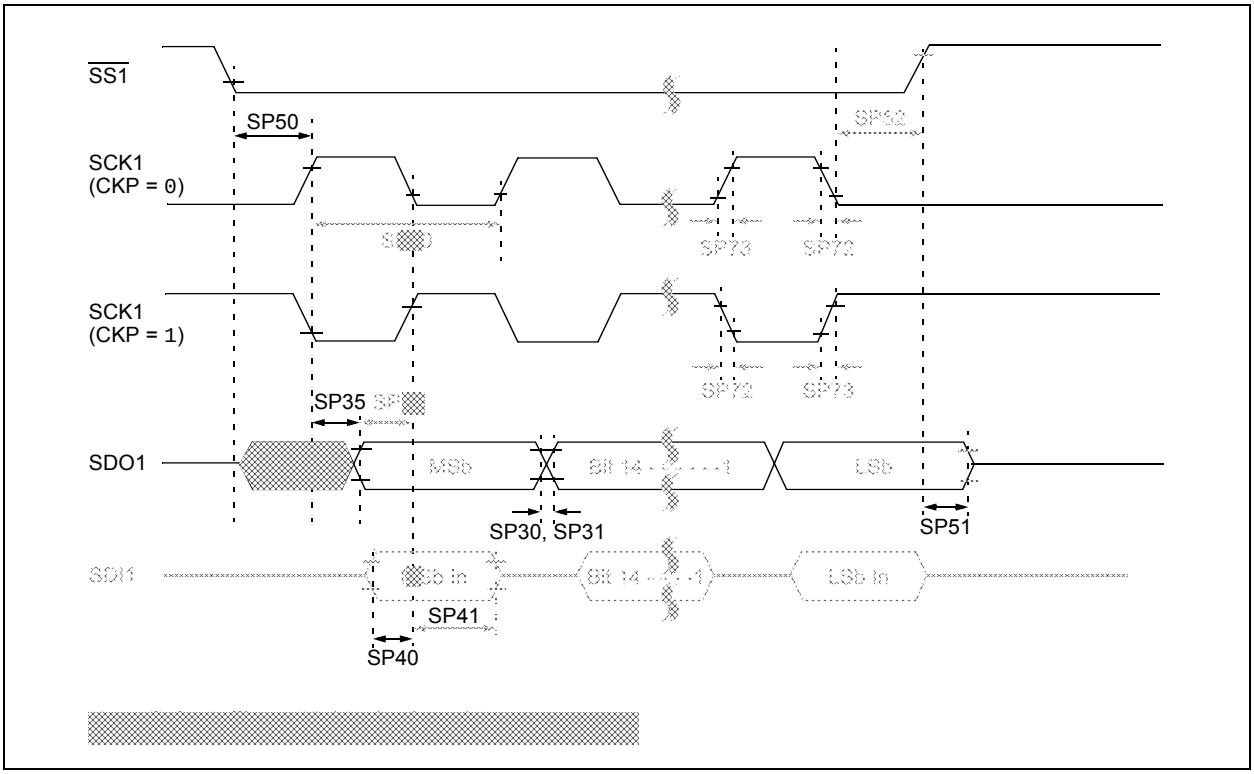
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 40 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

FIGURE 30-26: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



31.2 AC Characteristics and Timing Parameters

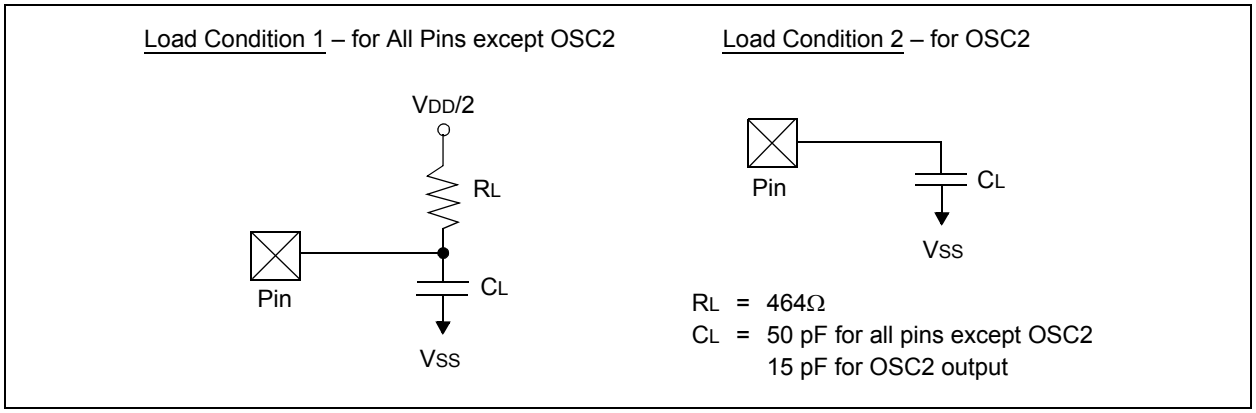
The information contained in this section defines the dsPIC33EVXXXGM00X/10X family AC characteristics and timing parameters for high-temperature devices. However, all AC timing specifications in this section are the same as those in **Section 30.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter OS53 in **Section 30.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 31-12: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

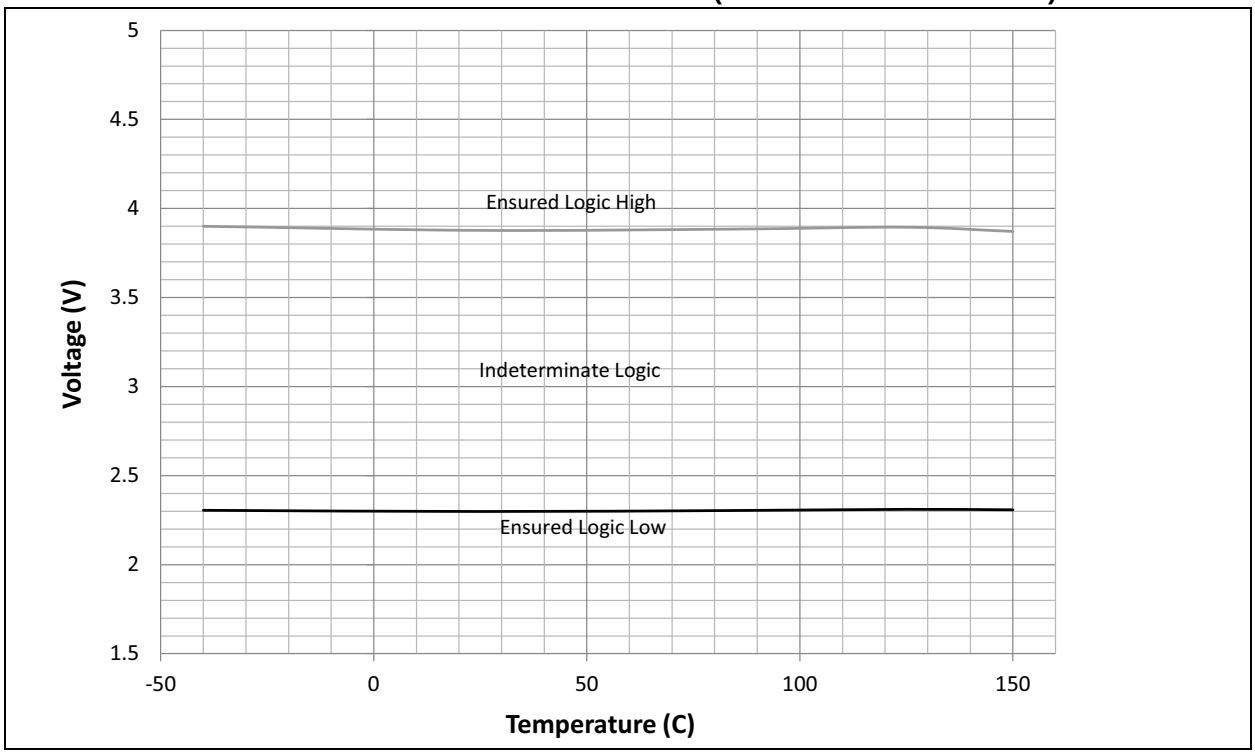
AC CHARACTERISTICS	**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



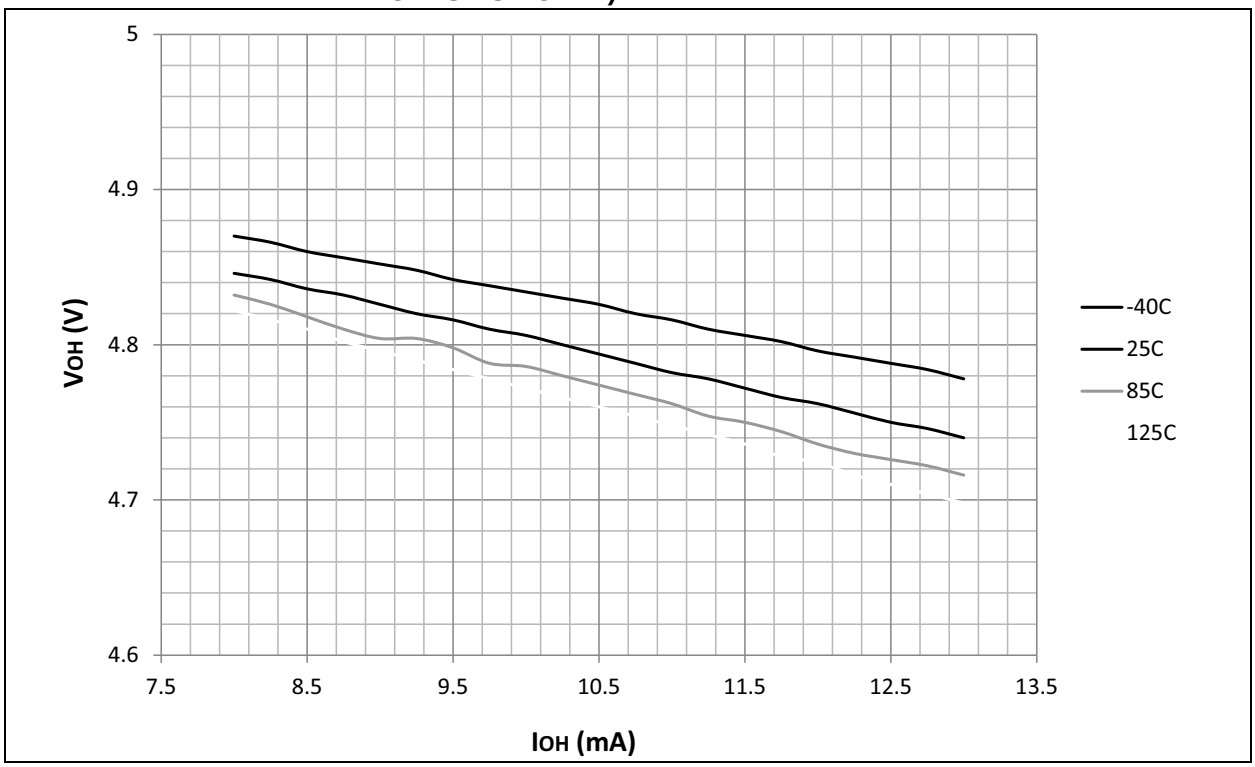
32.9 Voltage Input Low (VIL) – Voltage Input High (VIH)

FIGURE 32-29: TYPICAL VIH/VIL vs. TEMPERATURE (GENERAL PURPOSE I/Os)



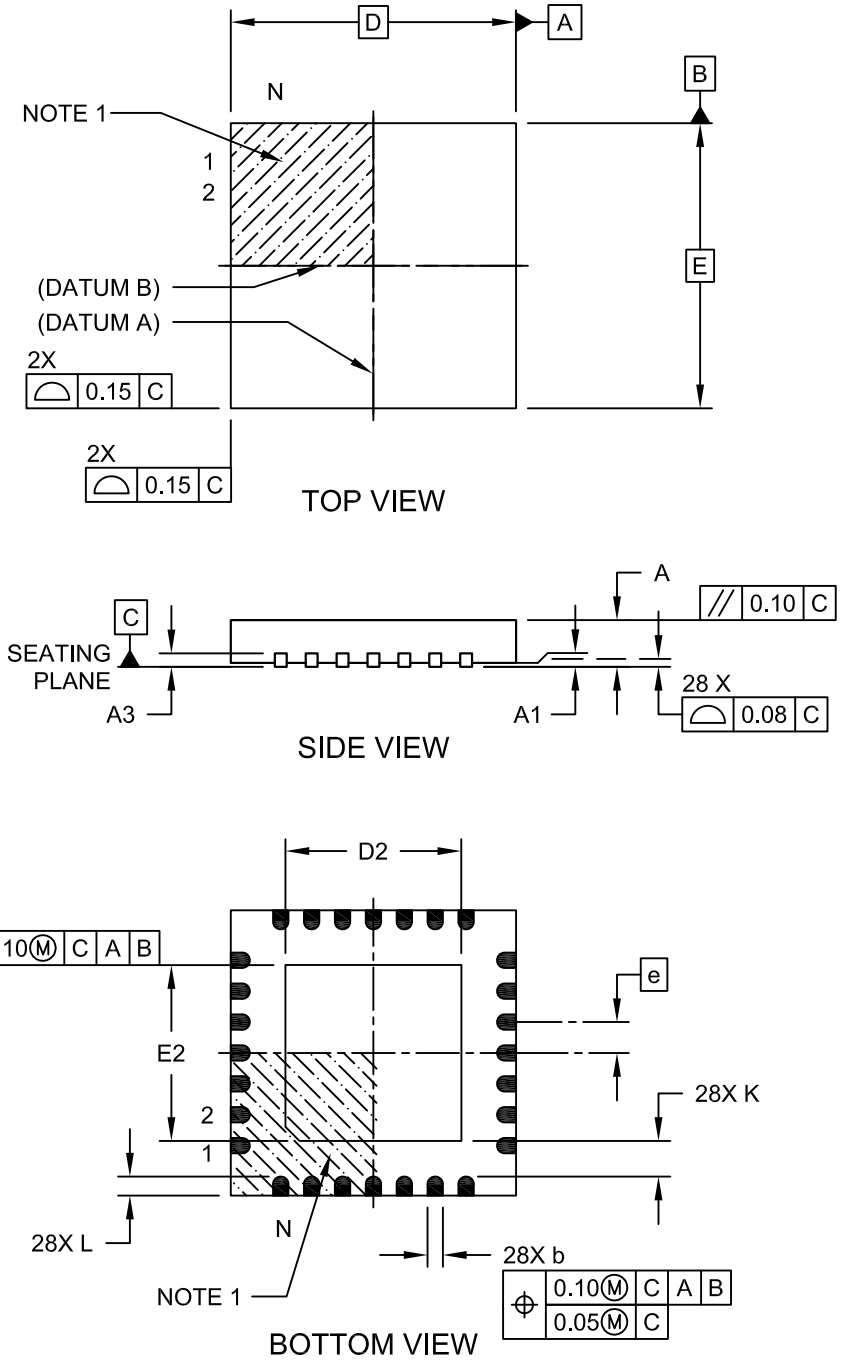
32.10 Voltage Output Low (VOL) – Voltage Output High (VOH)

FIGURE 32-30: TYPICAL VOH 8x DRIVER PINS vs. IOH (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)



28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S]
With 0.40 mm Terminal Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-124C Sheet 1 of 2